otal Num. Of Vias:	11.	-10		
58% UNIDAROSA	in statem statem			Min. Annular Ring (mm):
um, of Pads With Circ	cular Plated Holes:			Max. Aspect Ratio:
um. of Pads With Circ	cular Unplated Holes:		0	Min. Track Width (mm):
otal Num. of Circu	lar Holes (incl. vias):			1
				Num. Copper Layers:
lum. of Pads With Slotted Plated Holes:				Board Width (bounding rectangle, mm):
um. of Pads With Slo				Board Height (bounding rectangle, mm):
	tted Unplated Holes:			board Height (bounding rectangle, mm):
um. of Pads With Slo	ed Holes:			Board Area (bounding rectangle, mm^2):
um. of Pads With Slo  otal Num. of Slotte  otal Num. of Holes  ailing Infe	ed Holes:  s (circular and slotted):  ormation  Language: Reciepient:	(		For these costs are no in section
um. of Pads With Slo otal Num. of Slotte otal Num. of Holes ailing Infe	ed Holes:  s (circular and slotted):  ormation		Lead Time:	For the control of the state of